Lattice Semiconductor Corporation - LFEC3E-5QN208C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3100
Total RAM Bits	56320
Number of I/O	145
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec3e-5qn208c

Table 2-7. Maximum Number of Elements in a Block

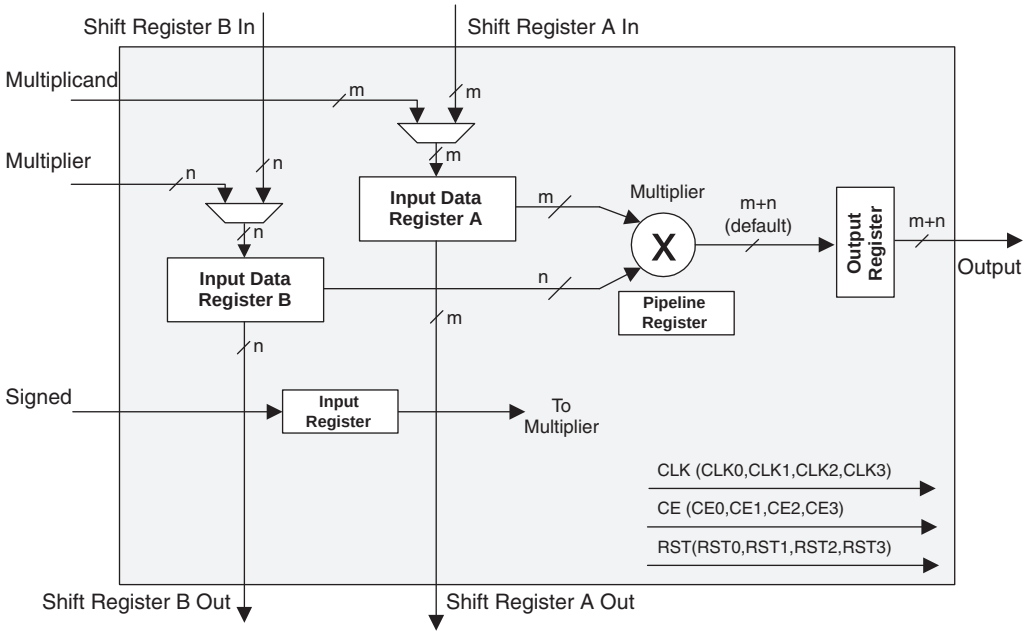
Width of Multiply	x9	x18	x36
MULT	8	4	1
MAC	2	2	—
MULTADD	4	2	—
MULTADDSUM	2	1	—

Some options are available in four elements. The input register in all the elements can be directly loaded or can be loaded as shift registers from previous operand registers. In addition by selecting “dynamic operation” in the ‘Signed/Unsigned’ options the operands can be switched between signed and unsigned on every cycle. Similarly by selecting ‘Dynamic operation’ in the ‘Add/Sub’ option the Accumulator can be switched between addition and subtraction on every cycle.

MULT sysDSP Element

This multiplier element implements a multiply with no addition or accumulator nodes. The two operands, A and B, are multiplied and the result is available at the output. The user can enable the input/output and pipeline registers. Figure 2-19 shows the MULT sysDSP element.

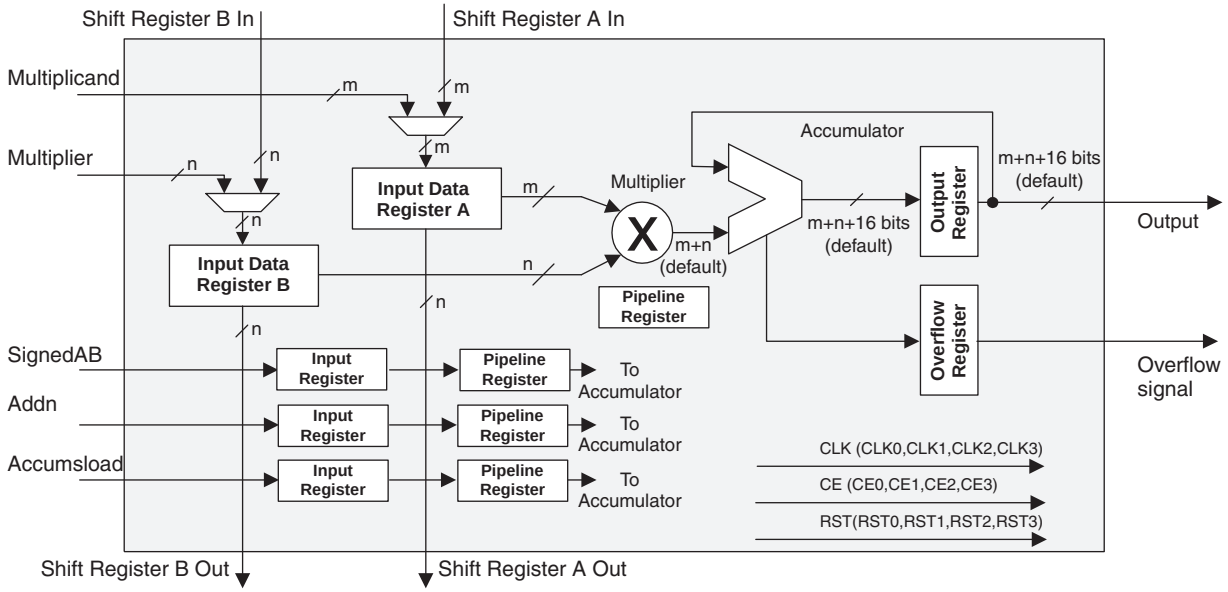
Figure 2-19. MULT sysDSP Element



MAC sysDSP Element

In this case the two operands, A and B, are multiplied and the result is added with the previous accumulated value. This accumulated value is available at the output. The user can enable the input and pipeline registers but the output register is always enabled. The output register is used to store the accumulated value. A registered overflow signal is also available. The overflow conditions are provided later in this document. Figure 2-20 shows the MAC sysDSP element.

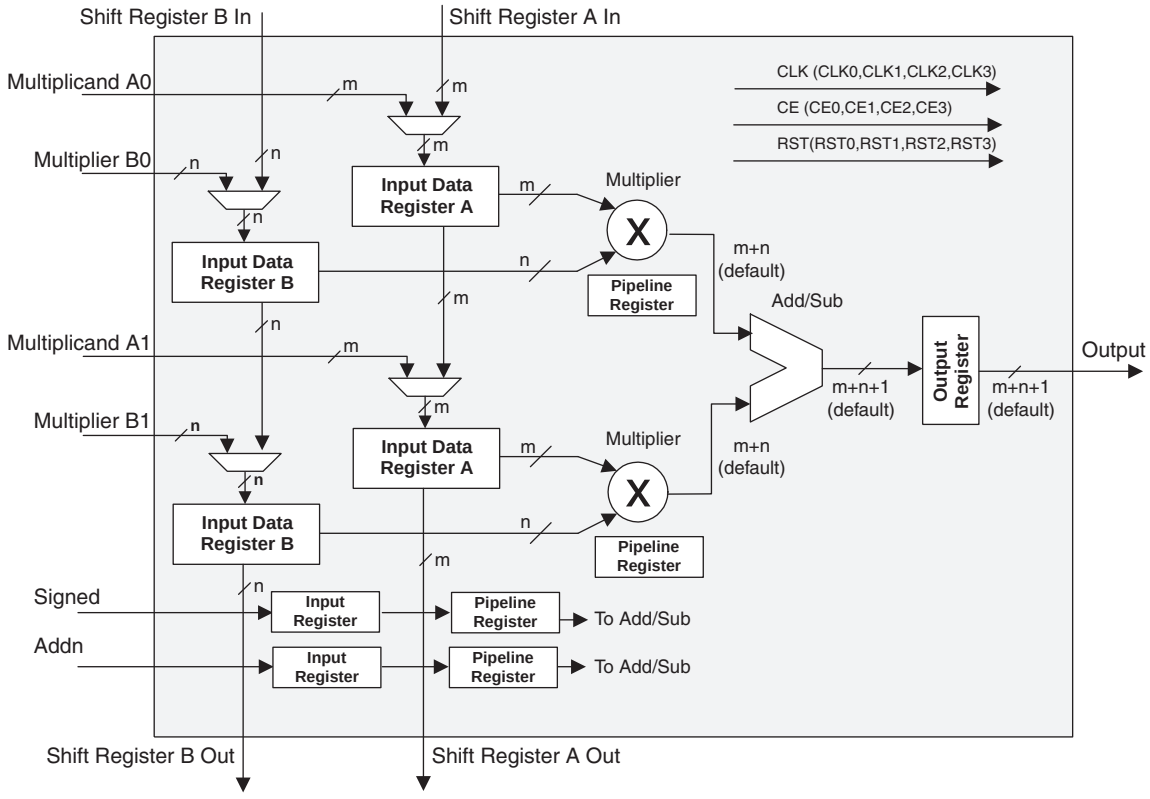
Figure 2-20. MAC sysDSP Element



MULTADD sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and A2. The user can enable the input, output and pipeline registers. Figure 2-21 shows the MULTADD sysDSP element.

Figure 2-21. MULTADD



Signed and Unsigned with Different Widths

The DSP block supports different widths of signed and unsigned multipliers besides x9, x18 and x36 widths. For unsigned operands, unused upper data bits should be filled to create a valid x9, x18 or x36 operand. For signed two's complement operands, sign extension of the most significant bit should be performed until x9, x18 or x36 width is reached. Table 2-8 provides an example of this.

Table 2-8. An Example of Sign Extension

Number	Unsigned	Unsigned 9-bit	Unsigned 18-bit	Signed	Two's Complement Signed 9-Bits	Two's Complement Signed 18-bits
+5	0101	000000101	000000000000000101	0101	000000101	000000000000000101
-6	0110	000000110	000000000000000110	1010	111111010	111111111111111010

OVERFLOW Flag from MAC

The sysDSP block provides an overflow output to indicate that the accumulator has overflowed. When two unsigned numbers are added and the result is a smaller number then accumulator roll over is said to occur and overflow signal is indicated. When two positive numbers are added with a negative sum and when two negative numbers are added with a positive sum, then the accumulator "roll-over" is said to have occurred and an overflow signal is indicated. Note when overflow occurs the overflow flag is present for only one cycle. By counting these overflow pulses in FPGA logic, larger accumulators can be constructed. The conditions overflow signals for signed and unsigned operands are listed in Figure 2-23.

Figure 2-23. Accumulator Overflow/Underflow Conditions

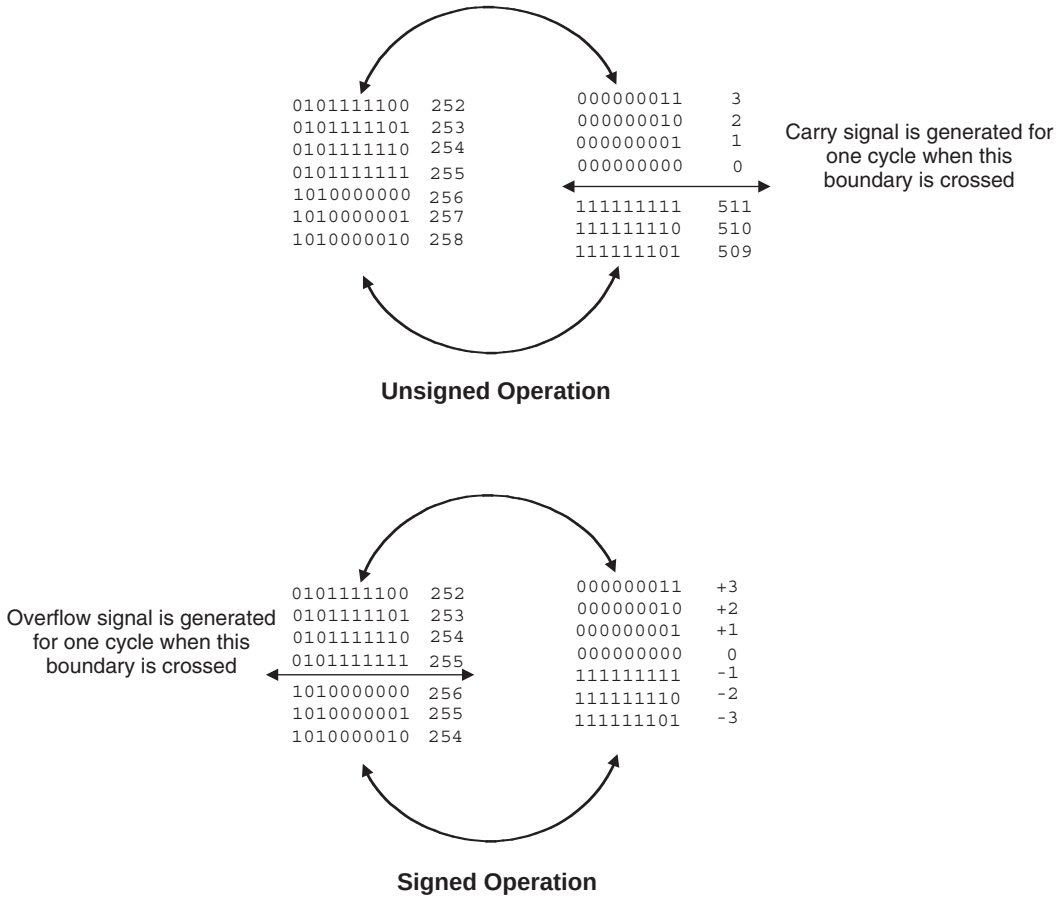


Figure 2-27. Input Register DDR Waveforms

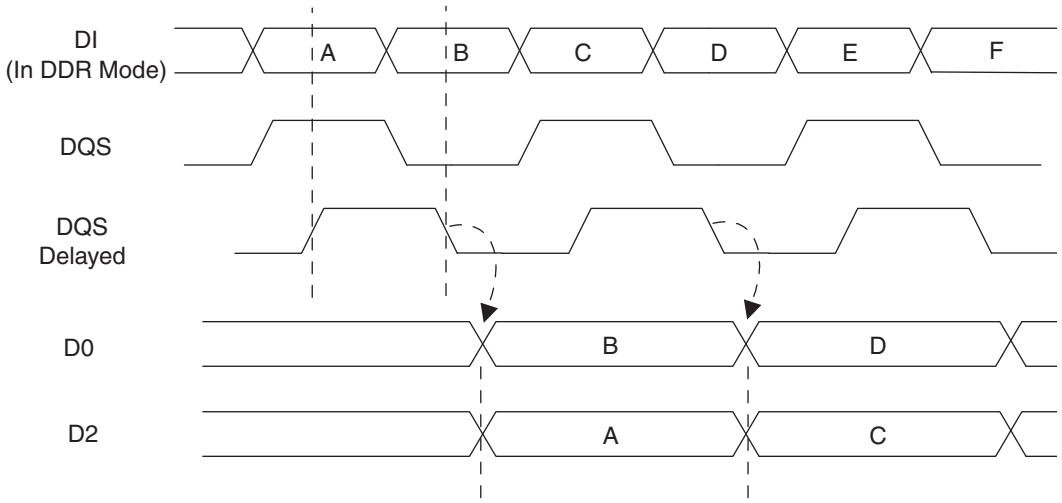
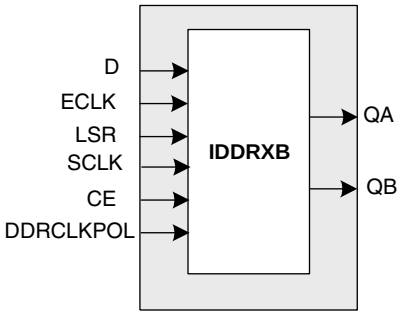


Figure 2-28. INDDRXB Primitive



Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysI/O buffers. The block contains a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-29 shows the diagram of the Output Register Block.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG0 is fed into one register on the positive edge of the clock and OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-30 shows the design tool DDR primitives. The SDR output register has reset and clock enable available. The additional register for DDR operation does not have reset or clock enable available.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. For more information about controlling the output logic state with valid input logic levels during power-up in LatticeECP/EC devices, see the list of technical documentation at the end of this data sheet.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered-up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported Standards

The LatticeECP/EC sysI/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5 and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, BLVDS, LVPECL, RSDS, differential SSTL and differential HSTL. Tables 2-13 and 2-14 show the I/O standards (together with their supply and reference voltages) supported by the LatticeECP/EC devices. For further information about utilizing the sysI/O buffer to support a variety of standards please see the the list of technical information at the end of this data sheet.

Table 2-13. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33[2]	—	—
LVCMOS25[2]	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12[2]	—	—
PCI	—	3.3
HSTL18 Class I, II	0.9	—
HSTL18 Class III	1.08	—
HSTL15 Class I	0.75	—
HSTL15 Class III	0.9	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I	0.9	—
Differential Interfaces		
Differential SSTL18 Class I	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I, III	—	—
Differential HSTL18 Class I, II, III	—	—
LVDS, LVPECL, BLVDS, RSDS	—	—

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.
2. JTAG inputs do not have a fixed threshold option and always follow V_{CCJ}.

sysI/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}[1] (mA)	I_{OH}[1] (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

LatticeECP/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL)[1]									
t_{CO}[7]	Clock to Output - PIO Output Register	LFEC1	—	5.09	—	6.11	—	7.13	ns
		LFEC3	—	5.71	—	6.85	—	7.99	ns
		LFEC6	—	5.60	—	6.72	—	7.84	ns
		LFEC10	—	5.47	—	6.57	—	7.66	ns
		LFEC15	—	5.67	—	6.81	—	7.94	ns
		LFEC20	—	5.89	—	7.07	—	8.25	ns
		LFEC33	—	6.19	—	7.42	—	8.66	ns
t_{SU}[7]	Clock to Data Setup - PIO Input Register	LFEC1	-0.08	—	-0.10	—	-0.12	—	ns
		LFEC3	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC6	-0.63	—	-0.76	—	-0.89	—	ns
		LFEC10	-0.43	—	-0.52	—	-0.61	—	ns
		LFEC15	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC20	-0.88	—	-1.06	—	-1.24	—	ns
		LFEC33	-1.12	—	-1.34	—	-1.56	—	ns
t_{H}[7]	Clock to Data Hold - PIO Input Register	LFEC1	2.19	—	2.62	—	3.06	—	ns
		LFEC3	2.80	—	3.36	—	3.92	—	ns
		LFEC6	2.69	—	3.23	—	3.77	—	ns
		LFEC10	2.56	—	3.08	—	3.59	—	ns
		LFEC15	2.76	—	3.32	—	3.87	—	ns
		LFEC20	2.99	—	3.58	—	4.18	—	ns
		LFEC33	3.28	—	3.93	—	4.59	—	ns
t_{SU_DEL}[7]	Clock to Data Setup - PIO Input Register with Data Input Delay	LFEC1	3.36	—	4.03	—	4.70	—	ns
		LFEC3	2.74	—	3.29	—	3.84	—	ns
		LFEC6	2.81	—	3.37	—	3.93	—	ns
		LFEC10	3.01	—	3.61	—	4.21	—	ns
		LFEC15	2.74	—	3.29	—	3.83	—	ns
		LFEC20	2.56	—	3.07	—	3.58	—	ns
		LFEC33	2.32	—	2.79	—	3.25	—	ns
t_{H_DEL}[7]	Clock to Data Hold - PIO Input Register with Input Data Delay	LFEC1	-1.31	—	-1.57	—	-1.83	—	ns
		LFEC3	-0.70	—	-0.83	—	-0.97	—	ns
		LFEC6	-0.80	—	-0.96	—	-1.12	—	ns
		LFEC10	-0.93	—	-1.12	—	-1.30	—	ns
		LFEC15	-0.73	—	-0.88	—	-1.02	—	ns
		LFEC20	-0.51	—	-0.61	—	-0.71	—	ns
		LFEC33	-0.22	—	-0.26	—	-0.30	—	ns
f_{MAX_IO}[2]	Clock Frequency of I/O and PFU Register	All	—	420	—	378	—	340	Mhz
DDR I/O Pin Parameters[3, 4, 5]									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI

Timing Diagrams

PFU Timing Diagrams

Figure 3-6. Slice Single/Dual Port Write Cycle Timing

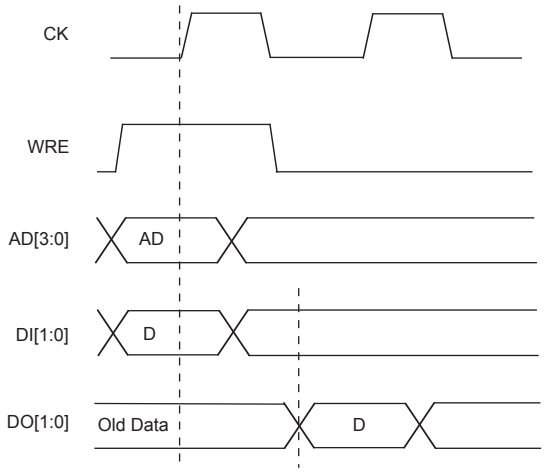
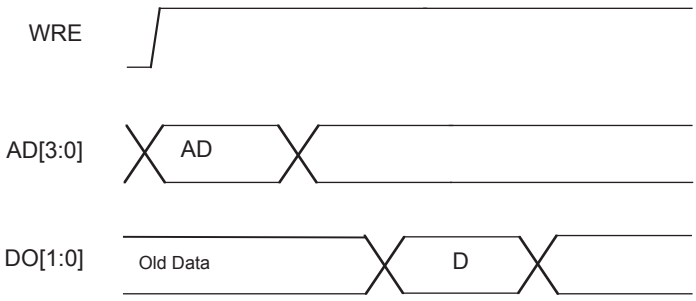


Figure 3-7. Slice Single /Dual Port Read Cycle Timing



LatticeECP/EC sysCONFIG Port Timing Specifications (Continued)

Over Recommended Operating Conditions

Parameter	Description	Min.	Typ.	Max.	Units
t_{SOE}	CSSPIN Active Setup Time	300		—	ns
t_{CSPID}	CSSPIN Low to First Clock Edge Setup Time	300+3cyc		600+6cyc	ns
f_{MAXSPI}	Max Frequency for SPI	—		25	MHz
t_{SUSPI}	SOSPI Data Setup Time Before CCLK	7		—	ns
t_{HSPI}	SOSPI Data Hold Time After CCLK	1		—	ns

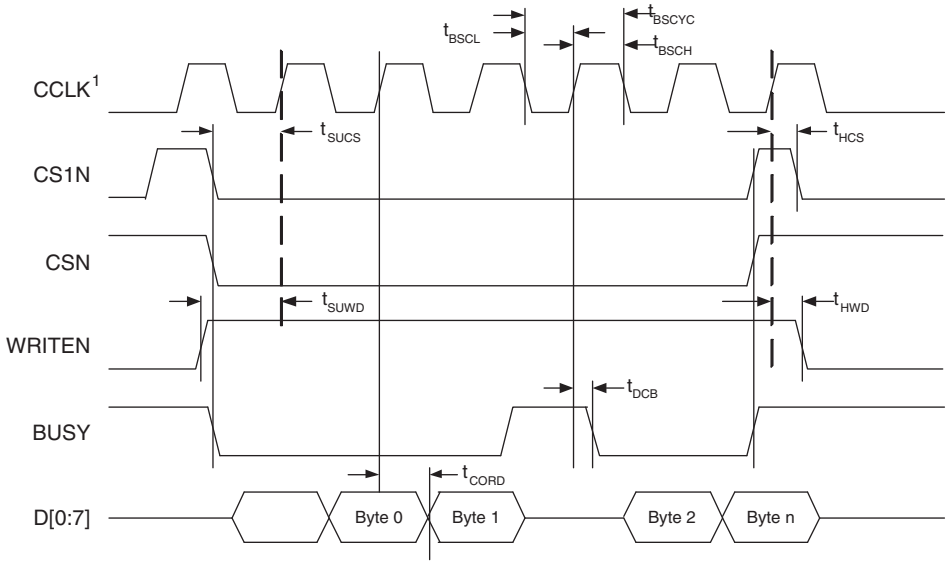
Timing v.G 0.30

Master Clock

Clock Mode	Min.	Typ.	Max.	Units
2.5MHz	1.75	2.5	3.25	MHz
5 MHz	3.78	5.4	7.02	MHz
10 MHz	7	10	13	MHz
15 MHz	10.5	15	19.5	MHz
20 MHz	14	20	26	MHz
25 MHz	18.2	26	33.8	MHz
30 MHz	21	30	39	MHz
35 MHz	23.8	34	44.2	MHz
40 MHz	28.7	41	53.3	MHz
45 MHz	31.5	45	58.5	MHz
50 MHz	35.7	51	66.3	MHz
55 MHz	38.5	55	71.5	MHz
60 MHz	42	60	78	MHz
Duty Cycle	40	—	60	%

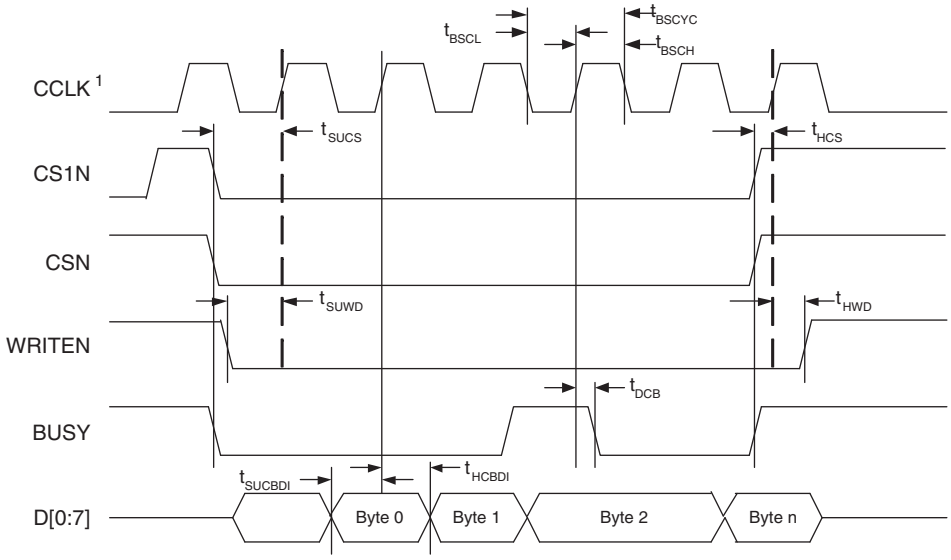
Timing v.G 0.30

Figure 3-12. sysCONFIG Parallel Port Read Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-13. sysCONFIG Parallel Port Write Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

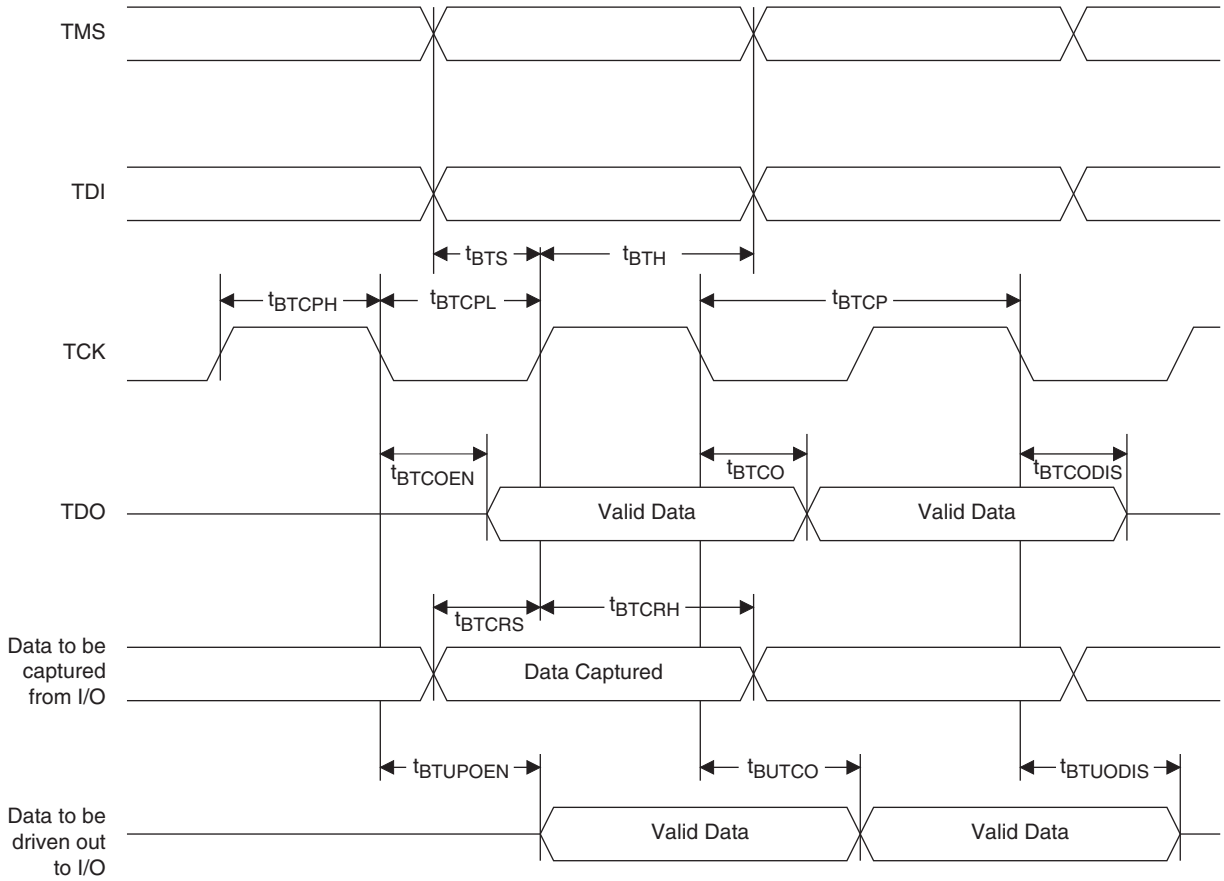
JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
f_{MAX}	TCK clock frequency	—	25	MHz
t_{BTCP}	TCK [BSCAN] clock pulse width	40	—	ns
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	8	—	ns
t_{BTH}	TCK [BSCAN] hold time	10	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	25	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

Timing v.G 0.30

Figure 3-20. JTAG Port Timing Waveforms



LFECP/EC6, LFECP/EC10 Logic Signal Connections: 208 PQFP

Pin Number	LFECP6/LFEC6				LFECP10/LFEC10			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
1*	GND0 GND7	-			GND0 GND7	-		
2	VCCIO7	7			VCCIO7	7		
3	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
4	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
5	NC	-			VCC	-		
6	NC	-			GND	-		
7	PL3B	7			PL12B	7		
8	PL4A	7	T		PL13A	7	T	
9	PL4B	7	C		PL13B	7	C	
10	PL5A	7	T		PL14A	7	T	
11	PL5B	7	C		PL14B	7	C	
12	PL6A	7	T	LDQS6	PL15A	7	T	LDQS15
13	VCCIO7	7			VCCIO7	7		
14	PL6B	7	C		PL15B	7	C	
15	PL7A	7	T		PL16A	7	T	
16	PL7B	7	C		PL16B	7	C	
17	PL8A	7	T		PL17A	7	T	
18	GND7	7			GND7	7		
19	PL8B	7	C		PL17B	7	C	
20	PL9A	7	T	PCLKT7_0	PL18A	7	T	PCLKT7_0
21	PL9B	7	C	PCLKC7_0	PL18B	7	C	PCLKC7_0
22	VCCAUX	-			VCCAUX	-		
23	XRES	6			XRES	6		
24	VCC	-			VCC	-		
25	GND	-			GND	-		
26	VCC	-			VCC	-		
27	TCK	6			TCK	6		
28	GND	-			GND	-		
29	TDI	6			TDI	6		
30	TMS	6			TMS	6		
31	TDO	6			TDO	6		
32	VCCJ	6			VCCJ	6		
33	PL20A	6	T	LLM0_PLLT_IN_A	PL29A	6	T	LLM0_PLLT_IN_A
34	PL20B	6	C	LLM0_PLLC_IN_A	PL29B	6	C	LLM0_PLLC_IN_A
35	PL21A	6	T	LLM0_PLLT_FB_A	PL30A	6	T	LLM0_PLLT_FB_A
36	PL21B	6	C	LLM0_PLLC_FB_A	PL30B	6	C	LLM0_PLLC_FB_A
37	VCCIO6	6			VCCIO6	6		
38	PL22A	6	T		PL31A	6	T	
39	PL22B	6	C		PL31B	6	C	
40	PL23A	6	T		PL32A	6	T	
41	GND6	6			GND6	6		
42	PL23B	6	C		PL32B	6	C	

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
K2	PL11A	6	T	LLM0_PLLT_IN_A	PL20A	6	T	LLM0_PLLT_IN_A
K1	PL11B	6	C	LLM0_PLLC_IN_A	PL20B	6	C	LLM0_PLLC_IN_A
L2	PL12A	6	T	LLM0_PLLT_FB_A	PL21A	6	T	LLM0_PLLT_FB_A
L1	PL12B	6	C	LLM0_PLLC_FB_A	PL21B	6	C	LLM0_PLLC_FB_A
M2	PL13A	6	T		PL22A	6	T	
M1	PL13B	6	C		PL22B	6	C	
N1	PL14A	6	T		PL23A	6	T	
GND	GND6	6			GND6	6		
N2	PL14B	6	C		PL23B	6	C	
M4	PL15A	6	T	LDQS15	PL24A	6	T	LDQS24
M3	PL15B	6	C		PL24B	6	C	
P1	PL16A	6	T		PL25A	6	T	
R1	PL16B	6	C		PL25B	6	C	
P2	PL17A	6	T		PL26A	6	T	
P3	PL17B	6	C		PL26B	6	C	
N3	PL18A	6	T	VREF1_6	PL27A	6	T	VREF1_6
N4	PL18B	6	C	VREF2_6	PL27B	6	C	VREF2_6
GND	GND6	6			GND6	6		
GND	GND5	5			GND5	5		
P4	PB2A	5	T		PB2A	5	T	
N5	PB2B	5	C		PB2B	5	C	
P5	PB3A	5	T		PB3A	5	T	
P6	PB3B	5	C		PB3B	5	C	
R4	PB4A	5	T		PB4A	5	T	
R3	PB4B	5	C		PB4B	5	C	
T2	PB5A	5	T		PB5A	5	T	
T3	PB5B	5	C		PB5B	5	C	
R5	PB6A	5	T	BDQS6	PB6A	5	T	BDQS6
R6	PB6B	5	C		PB6B	5	C	
T4	PB7A	5	T		PB7A	5	T	
T5	PB7B	5	C		PB7B	5	C	
N6	PB8A	5	T		PB8A	5	T	
M6	PB8B	5	C		PB8B	5	C	
T6	PB9A	5	T		PB9A	5	T	
GND	GND5	5			GND5	5		
T7	PB9B	5	C		PB9B	5	C	
P7	PB10A	5	T		PB10A	5	T	
N7	PB10B	5	C		PB10B	5	C	
R7	PB11A	5	T		PB11A	5	T	
R8	PB11B	5	C		PB11B	5	C	
M7	PB12A	5	T		PB12A	5	T	
M8	PB12B	5	C		PB12B	5	C	
T8	PB13A	5	T		PB13A	5	T	

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
N16	PR14A	3	T	RLM0_PLLT_FB_A	PR23A	3	T	RLM0_PLLT_FB_A
N15	PR13B	3	C	RLM0_PLLC_IN_A	PR22B	3	C	RLM0_PLLC_IN_A
M15	PR13A	3	T	RLM0_PLLT_IN_A	PR22A	3	T	RLM0_PLLT_IN_A
M16	PR12B	3	C	DI/CSSPIN	PR21B	3	C	DI/CSSPIN
L16	PR12A	3	T	DOUT/CSON	PR21A	3	T	DOUT/CSON
K16	PR11B	3	C	BUSY/SISPI	PR20B	3	C	BUSY/SISPI
J16	PR11A	3	T	D7/SPID0	PR20A	3	T	D7/SPID0
L12	CFG2	3			CFG2	3		
L14	CFG1	3			CFG1	3		
L13	CFG0	3			CFG0	3		
K13	PROGRAMN	3			PROGRAMN	3		
L15	CCLK	3			CCLK	3		
K15	INITN	3			INITN	3		
K14	DONE	3			DONE	3		
	-	-			GND3	3		
H16	NC	-			PR18B	3	C	
H15	NC	-			PR18A	3	T	
G16	NC	-			PR17B	3	C	
G15	NC	-			PR17A	3	T	
K12	NC	-			PR16B	3	C	
J12	NC	-			PR16A	3	T	
J14	NC	-			PR15B	3	C	
J15	NC	-			PR15A	3	T	RDQS15
F16	NC	-			PR14B	3	C	
-	-	-			GND3	3		
F15	NC	-			PR14A	3	T	
J13	NC	-			PR13B	3	C	
H13	NC	-			PR13A	3	T	
H14	NC	-			PR12B	3	C	
G14	NC	-			PR12A	3	T	
E16	NC	-			PR11B	3	C	
E15	NC	-			PR11A	3	T	
H12	PR9B	2	C	PCLKC2_0	PR9B	2	C	PCLKC2_0
GND	GND2	2			GND2			
G12	PR9A	2	T	PCLKT2_0	PR9A	2	T	PCLKT2_0
G13	PR8B	2	C		PR8B	2	C	
F13	PR8A	2	T		PR8A	2	T	
F12	PR7B	2	C		PR7B	2	C	
E13	PR7A	2	T		PR7A	2	T	
D16	PR6B	2	C		PR6B	2	C	
D15	PR6A	2	T	RDQS6	PR6A	2	T	RDQS6
F14	PR5B	2	C		PR5B	2	C	
E14	PR5A	2	T		PR5A	2	T	

LFECP/EC6, LFECP/EC10, LFECP/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP6/LFEC6					LFECP10/LFEC10					LFECP/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
C21	NC	-			C21	PR5B	2	C		C21	PR5B	2	C	
C20	NC	-			C20	PR5A	2	T		C20	PR5A	2	T	
F18	NC	-			F18	PR4B	2	C		F18	PR4B	2	C	
E18	NC	-			E18	PR4A	2	T		E18	PR4A	2	T	
B22	NC	-			B22	PR3B	2	C		B22	PR3B	2	C	
B21	NC	-			B21	PR3A	2	T		B21	PR3A	2	T	
E19	PR2B	2	C	VREF1_2	E19	PR2B	2	C	VREF1_2	E19	PR2B	2	C	VREF1_2
D19	PR2A	2	T	VREF2_2	D19	PR2A	2	T	VREF2_2	D19	PR2A	2	T	VREF2_2
GND	GND2	2			GND	GND2	2			GND	GND2	2		
GND	GND1	1			GND	GND1	1			GND	GND1	1		
G17	NC	-			G17	NC	-			G17	PT49B	1	C	
F17	NC	-			F17	NC	-			F17	PT49A	1	T	
D18	NC	-			D18	NC	-			D18	PT48B	1	C	
C18	NC	-			C18	NC	-			C18	PT48A	1	T	
C19	NC	-			C19	NC	-			C19	PT47B	1	C	
B20	NC	-			B20	NC	-			B20	PT47A	1	T	
D17	NC	-			D17	NC	-			D17	PT46B	1	C	
C16	NC	-			C16	NC	-			C16	PT46A	1	T	TDQS46
B19	NC	-			B19	NC	-			B19	PT45B	1	C	
GND	-	-			GND	-	-			GND	GND1	1		
A20	NC	-			A20	NC	-			A20	PT45A	1	T	
E17	NC	-			E17	NC	-			E17	PT44B	1	C	
C17	NC	-			C17	NC	-			C17	PT44A	1	T	
F16	NC	-			F16	NC	-			F16	PT43B	1	C	
E16	NC	-			E16	NC	-			E16	PT43A	1	T	
F15	NC	-			F15	NC	-			F15	PT42B	1	C	
D16	NC	-			D16	NC	-			D16	PT42A	1	T	
B18	PT33B	1	C		B18	PT41B	1	C		B18	PT41B	1	C	
GND	-	-			GND	-	-			GND	GND1	1		
A19	PT33A	1	T		A19	PT41A	1	T		A19	PT41A	1	T	
B17	PT32B	1	C		B17	PT40B	1	C		B17	PT40B	1	C	
A18	PT32A	1	T		A18	PT40A	1	T		A18	PT40A	1	T	
B16	PT31B	1	C		B16	PT39B	1	C		B16	PT39B	1	C	
A17	PT31A	1	T		A17	PT39A	1	T		A17	PT39A	1	T	
B15	PT30B	1	C		B15	PT38B	1	C		B15	PT38B	1	C	
A16	PT30A	1	T	TDQS30	A16	PT38A	1	T	TDQS38	A16	PT38A	1	T	TDQS38
A15	PT29B	1	C		A15	PT37B	1	C		A15	PT37B	1	C	
GND	GND1	1			GND	GND1	1			GND	GND1	1		
A14	PT29A	1	T		A14	PT37A	1	T		A14	PT37A	1	T	
G14	PT28B	1	C		G14	PT36B	1	C		G14	PT36B	1	C	
E15	PT28A	1	T		E15	PT36A	1	T		E15	PT36A	1	T	
D15	PT27B	1	C		D15	PT35B	1	C		D15	PT35B	1	C	
C15	PT27A	1	T		C15	PT35A	1	T		C15	PT35A	1	T	
C14	PT26B	1	C		C14	PT34B	1	C		C14	PT34B	1	C	
B14	PT26A	1	T		B14	PT34A	1	T		B14	PT34A	1	T	
A13	PT25B	1	C		A13	PT33B	1	C		A13	PT33B	1	C	
GND	GND1	1			GND	GND1	1			GND	GND1	1		
B13	PT25A	1	T		B13	PT33A	1	T		B13	PT33A	1	T	
E14	PT24B	1	C		E14	PT32B	1	C		E14	PT32B	1	C	
C13	PT24A	1	T		C13	PT32A	1	T		C13	PT32A	1	T	

LFECP/EC20 and LFECP/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP20/LFEC20					LFECP/LFEC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
C22	PR9A	2	T	RUM0_PLLT_FB_A	C22	PR17A	2	T	RUM0_PLLT_FB_A
G19	PR8B	2	C	RUM0_PLLC_IN_A	G19	PR16B	2	C	RUM0_PLLC_IN_A
G18	PR8A	2	T	RUM0_PLLT_IN_A	G18	PR16A	2	T	RUM0_PLLT_IN_A
F20	PR7B	2	C		F20	PR15B	2	C	
F19	PR7A	2	T		F19	PR15A	2	T	
E20	PR6B	2	C		E20	PR14B	2	C	
D20	PR6A	2	T	RDQS6	D20	PR14A	2	T	RDQS14
C21	PR5B	2	C		C21	PR13B	2	C	
GND	-	-			GND	GND2	2		
C20	PR5A	2	T		C20	PR13A	2	T	
F18	PR4B	2	C		F18	PR12B	2	C	
E18	PR4A	2	T		E18	PR12A	2	T	
B22	PR3B	2	C		B22	PR11B	2	C	
B21	PR3A	2	T		B21	PR11A	2	T	
GND	-	-			GND	GND2	2		
E19	PR2B	2	C	VREF1_2	E19	PR2B	2	C	VREF1_2
D19	PR2A	2	T	VREF2_2	D19	PR2A	2	T	VREF2_2
GND	GND2	2			GND	GND2	2		
GND	GND1	1			GND	GND1	1		
GND	-	-			GND	GND1	1		
G17	PT57B	1	C		G17	PT57B	1	C	
GND	-	-			GND	GND1	1		
F17	PT57A	1	T		F17	PT57A	1	T	
D18	PT56B	1	C		D18	PT56B	1	C	
C18	PT56A	1	T		C18	PT56A	1	T	
C19	PT55B	1	C		C19	PT55B	1	C	
B20	PT55A	1	T		B20	PT55A	1	T	
D17	PT54B	1	C		D17	PT54B	1	C	
C16	PT54A	1	T	TDQS54	C16	PT54A	1	T	TDQS54
B19	PT53B	1	C		B19	PT53B	1	C	
GND	GND1	1			GND	GND1	1		
A20	PT53A	1	T		A20	PT53A	1	T	
E17	PT52B	1	C		E17	PT52B	1	C	
C17	PT52A	1	T		C17	PT52A	1	T	
F16	PT51B	1	C		F16	PT51B	1	C	
E16	PT51A	1	T		E16	PT51A	1	T	
F15	PT50B	1	C		F15	PT50B	1	C	
D16	PT50A	1	T		D16	PT50A	1	T	
B18	PT49B	1	C		B18	PT49B	1	C	
GND	GND1	1			GND	GND1	1		
A19	PT49A	1	T		A19	PT49A	1	T	
B17	PT48B	1	C		B17	PT48B	1	C	
A18	PT48A	1	T		A18	PT48A	1	T	
B16	PT47B	1	C		B16	PT47B	1	C	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
Y6	NC	-			Y6	PL62A	6	T	
W7	NC	-			W7	PL62B	6	C	
AA4	NC	-			AA4	PL63A	6	T	
AB3	NC	-			AB3	PL63B	6	C	
AC2	NC	-			AC2	PL64A	6	T	
-	-	-			GND	GND6	6		
AC3	NC	-			AC3	PL64B	6	C	
AA5	NC	-			AA5	PL65A	6	T	LDQS65
AB5	NC	-			AB5	PL65B	6	C	
AD3	NC	-			AD3	PL66A	6	T	
AD2	NC	-			AD2	PL66B	6	C	
AE1	NC	-			AE1	PL67A	6	T	
AD1	NC	-			AD1	PL67B	6	C	
AB4	PL48A	6	T	VREF1_6	AB4	PL68A	6	T	VREF1_6
AC4	PL48B	6	C	VREF2_6	AC4	PL68B	6	C	VREF2_6
GND	GND6	6			GND	GND6	6		
GND	GND5	5			GND	GND5	5		
AB6	PB2A	5	T		AB6	PB2A	5	T	
AA6	PB2B	5	C		AA6	PB2B	5	C	
AC7	PB3A	5	T		AC7	PB3A	5	T	
Y8	PB3B	5	C		Y8	PB3B	5	C	
AB7	PB4A	5	T		AB7	PB4A	5	T	
AA7	PB4B	5	C		AA7	PB4B	5	C	
AC6	PB5A	5	T		AC6	PB5A	5	T	
AC5	PB5B	5	C		AC5	PB5B	5	C	
AB8	PB6A	5	T	BDQS6	AB8	PB6A	5	T	BDQS6
AC8	PB6B	5	C		AC8	PB6B	5	C	
AE2	PB7A	5	T		AE2	PB7A	5	T	
AA8	PB7B	5	C		AA8	PB7B	5	C	
AF2	PB8A	5	T		AF2	PB8A	5	T	
Y9	PB8B	5	C		Y9	PB8B	5	C	
AD5	PB9A	5	T		AD5	PB9A	5	T	
GND	GND5	5			GND	GND5	5		
AD4	PB9B	5	C		AD4	PB9B	5	C	
AD8	PB10A	5	T		AD8	PB10A	5	T	
AC9	PB10B	5	C		AC9	PB10B	5	C	
AE3	PB11A	5	T		AE3	PB11A	5	T	
AB9	PB11B	5	C		AB9	PB11B	5	C	
AF3	PB12A	5	T		AF3	PB12A	5	T	
AD9	PB12B	5	C		AD9	PB12B	5	C	
AE4	PB13A	5	T		AE4	PB13A	5	T	
GND	GND5	5			GND	GND5	5		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
U12	GND	-			U12	GND	-		
U13	GND	-			U13	GND	-		
U14	GND	-			U14	GND	-		
U15	GND	-			U15	GND	-		
U16	GND	-			U16	GND	-		
U17	GND	-			U17	GND	-		
H10	VCC	-			H10	VCC	-		
H11	VCC	-			H11	VCC	-		
H16	VCC	-			H16	VCC	-		
H17	VCC	-			H17	VCC	-		
H18	VCC	-			H18	VCC	-		
H19	VCC	-			H19	VCC	-		
H8	VCC	-			H8	VCC	-		
H9	VCC	-			H9	VCC	-		
J18	VCC	-			J18	VCC	-		
J9	VCC	-			J9	VCC	-		
K8	VCC	-			K8	VCC	-		
L19	VCC	-			L19	VCC	-		
M19	VCC	-			M19	VCC	-		
N7	VCC	-			N7	VCC	-		
R20	VCC	-			R20	VCC	-		
R7	VCC	-			R7	VCC	-		
T19	VCC	-			T19	VCC	-		
V18	VCC	-			V18	VCC	-		
V8	VCC	-			V8	VCC	-		
V9	VCC	-			V9	VCC	-		
W10	VCC	-			W10	VCC	-		
W11	VCC	-			W11	VCC	-		
W16	VCC	-			W16	VCC	-		
W17	VCC	-			W17	VCC	-		
W18	VCC	-			W18	VCC	-		
W19	VCC	-			W19	VCC	-		
W8	VCC	-			W8	VCC	-		
W9	VCC	-			W9	VCC	-		
H12	VCCIO0	0			H12	VCCIO0	0		
H13	VCCIO0	0			H13	VCCIO0	0		
J10	VCCIO0	0			J10	VCCIO0	0		
J11	VCCIO0	0			J11	VCCIO0	0		
J12	VCCIO0	0			J12	VCCIO0	0		
J13	VCCIO0	0			J13	VCCIO0	0		
H14	VCCIO1	1			H14	VCCIO1	1		
H15	VCCIO1	1			H15	VCCIO1	1		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
H7	VCCAUX	-			H7	VCCAUX	-		
J19	VCCAUX	-			J19	VCCAUX	-		
J8	VCCAUX	-			J8	VCCAUX	-		
K7	VCCAUX	-			K7	VCCAUX	-		
L20	VCCAUX	-			L20	VCCAUX	-		
M20	VCCAUX	-			M20	VCCAUX	-		
M7	VCCAUX	-			M7	VCCAUX	-		
N20	VCCAUX	-			N20	VCCAUX	-		
P20	VCCAUX	-			P20	VCCAUX	-		
P7	VCCAUX	-			P7	VCCAUX	-		
T20	VCCAUX	-			T20	VCCAUX	-		
T7	VCCAUX	-			T7	VCCAUX	-		
T8	VCCAUX	-			T8	VCCAUX	-		
V19	VCCAUX	-			V19	VCCAUX	-		
V7	VCCAUX	-			V7	VCCAUX	-		
W20	VCCAUX	-			W20	VCCAUX	-		
Y13	VCCAUX	-			Y13	VCCAUX	-		
Y7	VCCAUX	-			Y7	VCCAUX	-		
K19	VCC[1]	-			K19	VCCPLL	-		
L8	VCC[1]	-			L8	VCCPLL	-		
U19	VCC[1]	-			U19	VCCPLL	-		
U8	VCC[1]	-			U8	VCCPLL	-		

1. Tied to V_{CCPLL}.

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software